

Title of Change:	Replace Gold Wire with bare Copper Wire, and replace Hitachi compound with Hysol compound, for MOSFET Products in onsemi Leshan, China		
Proposed Changed Material First Ship Date:	01 Apr 2023 or earlier if approved by customer		
Current Material Last Order Date:	30 Dec 2022 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	31 Mar 2023 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Discrete components		
Contact information:	Contact your local onsemi Sales Office or York.Yu@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	10 Oct 2022		
PPAP Availability Date:	30 Dec 2022		
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>c.l.yang@lps.com.cn</u>		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <u>PCN.Support@onsemi.com</u> .		
Change Category			
Category	Type of Change		
Process - Assembly	Change of mold compound, Change of wire bonding		

Description and Purpose:

onsemi is notifying customers to replace 0.8mil Gold wire with 0.8mil bare Copper Wire, and replace Hitachi GE-200F to Hysol GR640 HV for mold compound, for their SOT23 and SC88 package Mosfet Products assembled at Leshan site, China.

<u>Purpose for changing</u>: Copper wire has higher Thermal conductivity and lower Resistivity which indicate better thermal dissipation. And Hysol compound has better fluidity.

		From	То	
Bond Wire		0.8mil Gold wire	0.8mil Bare copper wire	
Mold Compound	Hitachi GE-200F Hysol GR640 HV		Hysol GR640 HV	
Reason / Motivation for Change:	Process/Materials Change			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.			

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onsemi Sites onsemi Leshan, China		External Foundry/Subcon Sites None				
					Marking of Parts/ Traceability of Traceability will be maintaine	
eliability Data	Summary:					
V DEVICE NAM MS#: L83376 ACKAGE: SOT23	3			Condition	Internel	Desults
Test HTRB	Specificatio JESD22-A10		Ta=150°C, 100	Condition	Interval 1008 hrs	Results 0/231
HTGB	JESD22-A10 JESD22-A10			% max rated Vgss	1008 hrs	0/231
HTGB	JESD22-A10 JESD22-A10	-	Ta=150°C, 100	% max rateu vgss	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101		Ta=+25°C, delta Tj=100°C On/off = 2 min		30К сус	0/231
тс	JESD22-A10	04 Ta= -65°C to +		150°C	1000 cyc	0/231
HAST	JESD22-A11	0	130°C, 85% R⊦	I, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A11	8	130°C, 85% R⊦	I, 18.8psig, unbiased	96 hrs	0/231
unasi	J-STD-020 JESD-	A113		MSL 1 @ 260 °C	-	
PC		06		Ta = 265C, 10 sec	-	0/30
	JESD22- B10	6				0/30

4. Then click on the attached file.

Electrical Characteristics Summary:

Electrical characteristics are not impacted, detail data summary can be provided upon customer requirement.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal.**

Current Part Number	New Part Number	Qualification Vehicle
NVTR0202PLT1G	NA	BSS123-G
MVMBF0201NLT1G	NA	BSS123-G

Appendix A: Changed Products

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NVTR0202PLT1G		BSS123-G	NA	
MVMBF0201NLT1G		BSS123-G	NA	